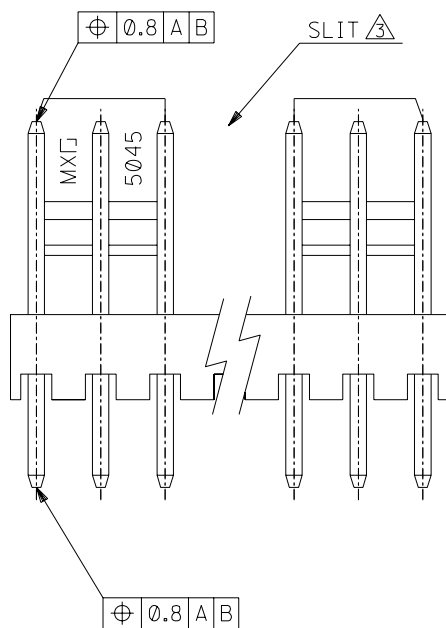
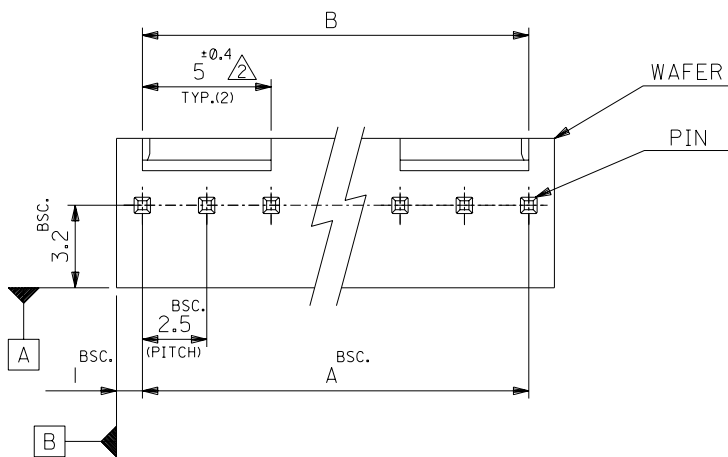
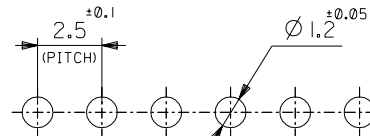




(NON ACCUMULATIVE)



RECOMMENDED P.C. BOARD HOLE DIM.

NOTES

I. MATERIAL

WAFER : 66NYLON UL94V-0

PIN : $\square 0.635$

BRASS, GOLD(0.35 μ mMIN.)

OVER NICKEL(2 μ mMIN.) PLATING

△ TO BE APPLIED FOR 6CKT.
AND MORE THAN 6CKT.

△ NO SLIT IS PROVIDED FOR 5CKT.
AND LESS THAN 5CKT.

1.35	0.85	47.5 ^{+0.3} _{-0.45}	47.5	22-11-1201	5045-20AG	20
↑	↑	45 ^{+0.3} _{-0.45}	45	↑ -1191	↑ -19AG	19
		42.5 ^{+0.3} _{-0.45}	42.5	↑ -1181	↑ -18AG	18
		40 ^{+0.3} _{-0.45}	40	↑ -1171	↑ -17AG	17
		37.5 ^{+0.3} _{-0.45}	37.5	↑ -1161	↑ -16AG	16
		35 ^{+0.3} _{-0.45}	35	↑ -1151	↑ -15AG	15
		32.5 ^{+0.25} _{-0.45}	32.5	↑ -1141	↑ -14AG	14
		30 ^{+0.25} _{-0.4}	30	↑ -1131	↑ -13AG	13
		27.5 ^{+0.25} _{-0.4}	27.5	↑ -1121	↑ -12AG	12
		25 ^{+0.2} _{-0.4}	25	↑ -1111	↑ -11AG	11
		22.5 ^{+0.2} _{-0.4}	22.5	↑ -1101	↑ -10AG	10
		20 ^{+0.15} _{-0.35}	20	↑ -1091	↑ -09AG	9
		17.5 ^{+0.15} _{-0.35}	17.5	↑ -1081	↑ -08AG	8
		15 ^{+0.1} _{-0.3}	15	↑ -1071	↑ -07AG	7
		12.5 ^{+0.15} _{-0.3}	12.5	↑ -1061	↑ -06AG	6
		10 ^{+0.15} _{-0.3}	10	↑ -1051	↑ -05AG	5
1.35	0.85	7.5 ^{+0.15} _{-0.3}	7.5	↓ -1041	↓ -04AG	4
1.2	1	5 ^{+0.15} _{-0.3}	5	↓ -1031	↓ -03AG	3
1.2	1	2.5 ^{+0.15} _{-0.3}	2.5	22-11-1021	5045-02AG	2
D	C	B	A	EDP NO.	ENG. NO.	CKT.

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	REVISE ONLY ON CAD SYSTEM

記号	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
E	REVISED & REDRAWN (100300)	Y.M	'90/4/4

材料 MATERIAL	SEE NOTES
仕上げ FINISH	—//—
適用電線範囲 WIRE RANGE	—//—
被覆外径 INS. RANGE	—//—
DRAWN BY '90/3/23 Y.MIZUNO	CHK'D BY '91/2/10 M.FUKUSHIMA
APP'D BY '91/2/10 M.ENOMOTO	尺度 SCALE 5 - 1

molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
EDP. NO. 22-11-1**1	
ENG. NO. SD-5045-NAG	
REV E	
TITLE 名称 KK 2.5 WAFER ASS'Y WITH LOCK	

4